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ISM330DLC

iNEMO inertial module: 3D accelerometer and 3D gyroscope with digital output for industrial applications

Datasheet - production data

LGA-14L
(2.5 x 3 x 0.83 mm) typ.

Features

- 3D accelerometer with selectable full scale: ±2/±4/±8/±16 *g*
- 3D gyroscope with selectable full scale: ±125/±250/±500/±1000/±2000 dps
- Analog supply voltage: 1.71 V to 3.6 V
- SPI & I²C serial interface with main processor data synchronization
- Dedicated gyroscope output chain with low latency, low noise and dedicated low-pass filters for control loop stability (OIS and other stabilization applications)
- Auxiliary SPI serial interface for independent, low-noise low-latency data output for gyroscope and accelerometer
- Ultra-low power consumption for both accelerometer and gyroscope enabling long-lasting battery-operated applications: 0.5 mA in combo normal mode and 0.75 mA in combo high-performance mode
- Smart FIFO up to 4 kbyte
- Smart embedded functions and interrupts: tilt detection, free-fall, wakeup, 6D/4D orientation, click and double-click
- Sensor hub feature to efficiently collect data from additional external sensors
- Embedded hard, soft ironing for external magnetic sensor corrections
- Embedded temperature sensor
- Embedded self-test both for gyroscope and accelerometer
- High shock survivability
- Extended operating temperature range (-40°C to +85°C)
- ECOPACK®, RoHS and “Green” compliant

Applications

- Industrial IoT and connected devices
- Antennas, platforms, and optical image and lens stabilization
- Robotics, drones and industrial automation
- Navigation systems and telematics
- Vibration monitoring and compensation

Description

The ISM330DLC is a system-in-package featuring a high-performance 3D digital accelerometer and 3D digital gyroscope tailored for Industry 4.0 applications.

ST’s family of MEMS sensor modules leverages the robust and mature manufacturing processes already used for the production of micromachined accelerometers and gyroscopes.

The various sensing elements are manufactured using specialized micromachining processes, while the IC interfaces are developed using CMOS technology that allows the design of a dedicated circuit which is trimmed to better match the characteristics of the sensing element.

In the ISM330DLC the sensing element of the accelerometer and of the gyro are implemented on the same silicon die, thus guaranteeing superior stability and robustness.

The ISM330DLC has a full-scale acceleration range of ±2/±4/±8/±16 *g* and an angular rate range of ±125/±250/±500/±1000/±2000 dps.

Delivering high accuracy and stability with ultra-low power consumption (0.75 mA in high-performance, combo mode) enables, also in the industrial domain, long-lasting battery-operated applications.

The ISM330DLC includes a dedicated configurable signal processing path with low latency, low noise and dedicated filtering specifically intended for control loop stability. Data from this dedicated signal path can be made available through an auxiliary SPI interface, configurable for both the gyroscope and accelerometer. High-performance, high-quality, small size and low power consumption together with high robustness to mechanical shock makes the ISM330DLC the preferred choice of system designers for the creation and manufacturing of versatile and reliable products.

The ISM330DLC is available in a plastic, land grid array (LGA) package.

Table 1. Device summary

Part number	Temp. range [°C]	Package	Packing
ISM330DLCTR	-40 to +85	LGA-14L (2.5x3x0.83mm)	Tape & Reel

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1 Overview

The ISM330DLC is a system-in-package featuring a high-performance 3D digital accelerometer and 3D digital gyroscope tailored for Industry 4.0 applications.

The ISM330DLC has a full-scale acceleration range of ±2/±4/±8/±16 g, an angular rate range of ±125/±250/±500/±1000/±2000 dps and is capable of delivering highly accurate and reliable measurements at an ultra-low power consumption (0.75 mA in high-performance, combo mode).

The ISM330DLC embeds smart features which simplify and optimize the application design and allows the usage of complex motion-sensing information also in power-constrained applications

The event-detection interrupts enable efficient and reliable motion tracking and contextual awareness, implementing hardware recognition of free-fall events, 6D orientation, click and double-click sensing, activity or inactivity, and wakeup events.

Up to 4 kbyte of FIFO with dynamic allocation of significant data (i.e. external sensors, timestamp, etc.) allows overall power saving of the system and protects against any loss of data.

With the sensor hub feature, data from up to 4 external sensors can be collected and stored in the internal FIFO without intervention of the application microcontroller.

Moreover, the ISM330DLC offers specific support, both for the gyroscope and the accelerometer, to applications requiring closed control loop. The device, through a dedicated auxiliary SPI interface and a configurable signal processing path having low latency and low noise, can provide data for the control loop while, at the same time, a second fully independent path can output data for other application intents.

Like the entire portfolio of MEMS sensor modules, the ISM330DLC leverages the robust and mature in-house manufacturing processes already used for the production of micromachined accelerometers and gyroscopes. The various sensing elements are manufactured using specialized micromachining processes, while the IC interfaces are developed using CMOS technology that allows the design of a dedicated circuit which is trimmed to better match the characteristics of the sensing element.

In the ISM330DLC, the sensing element of the accelerometer and of the gyroscope are implemented on the same silicon die, thus guaranteeing superior stability and robustness.

The ISM330DLC is available in a small plastic land grid array (LGA) package of 2.5 x 3.0 x 0.83 mm.

2 Embedded smart features

The ISM330DLC features the following on-chip smart functions:

- 4 kbyte data buffering
  - 100% efficiency with flexible configurations and partitioning
  - Possibility to store timestamp
- Event-detection interrupts (fully configurable):
  - Free-fall
  - Wakeup
  - 6D orientation
  - Click and double-click sensing
  - Activity / inactivity recognition
  - Tilt (refer to *Section 2.1: Tilt detection* for additional information
- Sensor hub
  - Up to 6 total sensors: 2 internal (accelerometer and gyroscope) and 4 external sensors
- Data rate synchronization with external trigger

2.1 Tilt detection

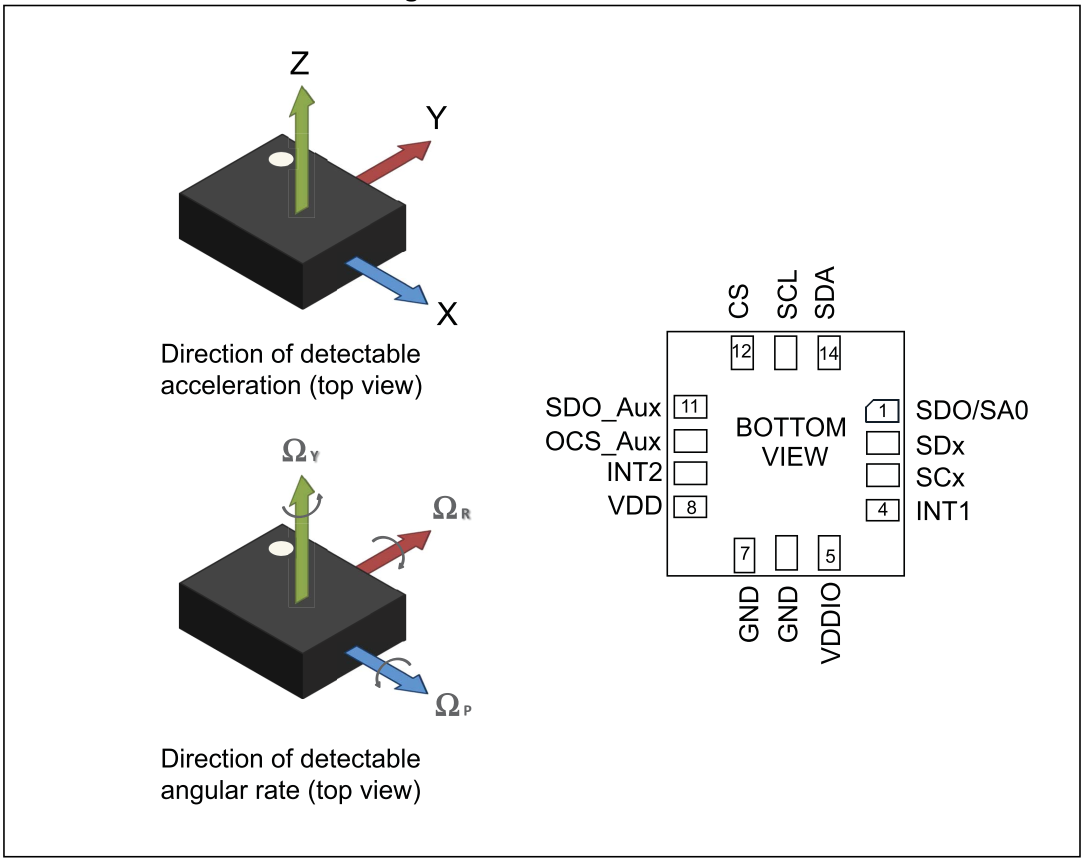
The tilt function helps to detect activity change and has been implemented in hardware using only the accelerometer to achieve both the targets of ultra-low power consumption and robustness during the short duration of dynamic accelerations.

The tilt function is based on a trigger of an event each time the device's tilt changes. It is configurable through:

- a programmable average window
- a programmable average threshold

3 Pin description

Figure 1. Pin connections

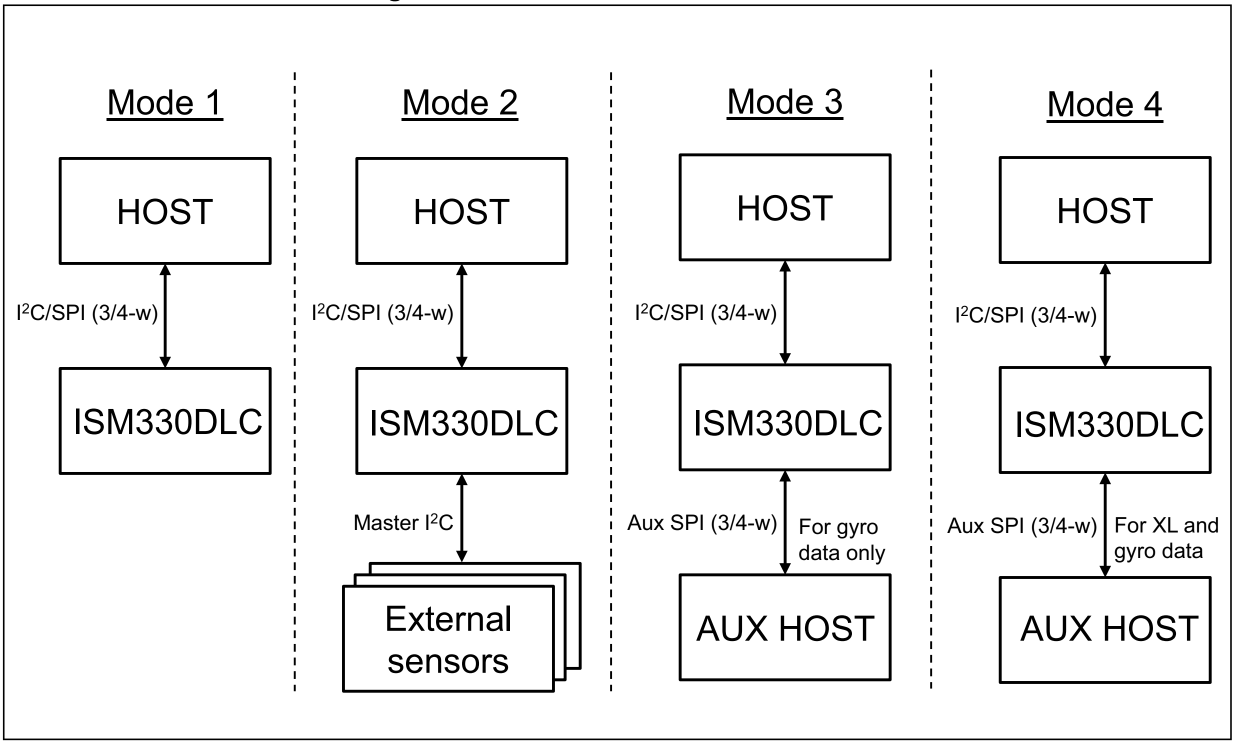


3.1 Pin connections

The ISM330DLC offers flexibility to connect the pins in order to have four different mode connections and functionalities. In detail:

- **Mode 1**: I^{2}C slave interface or SPI (3- and 4-wire) serial interface is available;
- **Mode 2**: I^{2}C slave interface or SPI (3- and 4-wire) serial interface and I^{2}C interface master for external sensor connections are available;
- **Mode 3:** I^{2}C slave interface or SPI (3- and 4-wire) serial interface is available for the application processor interface while an auxiliary SPI (3- and 4-wire) serial interface is available for an auxiliary host to access the gyroscope ONLY;
- **Mode 4:** I^{2}C slave interface or SPI (3- and 4-wire) serial interface is available for the application processor interface while an auxiliary SPI (3- and 4-wire) serial interface is available for an auxiliary host to access the accelerometer and gyroscope.

Figure 2. ISM330DLC connection modes



In the following table each mode is described for the pin connections and function.

Table 2. Pin description

Pin#	Name	Mode 1 function	Mode 2 function	Mode 3 / Mode 4 function
1	SDO/SA0	SPI 4-wire interface serial data output (SDO) I^2C least significant bit of the device address (SA0)	SPI 4-wire interface serial data output (SDO) I^2C least significant bit of the device address (SA0)	SPI 4-wire interface serial data output (SDO) I^2C least significant bit of the device address (SA0)
2	SDx	Connect to VDDIO or GND	I^2C serial data master (MSDA)	Auxiliary SPI 3/4-wire interface serial data input (SDI) and SPI 3-wire serial data output (SDO)
3	SCx	Connect to VDDIO or GND	I^2C serial clock master (MSCL)	Auxiliary SPI (3/4-wire) interface serial port clock (SPC_Aux)
4	INT1	Programmable interrupt 1		
5	VDDIO(1)	Power supply for I/O pins		
6	GND	0 V supply		
7	GND	0 V supply		
8	VDD(1)	Power supply		
9	INT2	Programmable interrupt 2 (INT2) / Data enable (DEN)	Programmable interrupt 2 (INT2)/ Data enable (DEN)/ I^2C master external synchronization signal (MDRDY)	Programmable interrupt 2 (INT2)/ Data enable (DEN)
10	OCS_Aux	Leave unconnected(2)	Leave unconnected(2)	Auxiliary SPI 3/4-wire interface enable
11	SDO_Aux	Connect to VDD_IO or leave unconnected(2)	Connect to VDD_IO or leave unconnected(2)	Auxiliary SPI 3-wire interface: leave unconnected(2) Auxiliary SPI 4-wire interface: serial data output (SDO_Aux)
12	CS	I^2C/SPI mode selection (1: SPI idle mode / I^2C communication enabled; 0: SPI communication mode / I^2C disabled)	I^2C/SPI mode selection (1: SPI idle mode / I^2C communication enabled; 0: SPI communication mode / I^2C disabled)	I^2C/SPI mode selection (1: SPI idle mode / I^2C communication enabled; 0: SPI communication mode / I^2C disabled)
13	SCL	I^2C serial clock (SCL) SPI serial port clock (SPC)	I^2C serial clock (SCL) SPI serial port clock (SPC)	I^2C serial clock (SCL) SPI serial port clock (SPC)
14	SDA	I^2C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)	I^2C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)	I^2C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)

1. Recommended 100 nF filter capacitor.
2. Leave pin electrically unconnected and soldered to PCB.

4 Module specifications

4.1 Mechanical characteristics

@ Vdd = 1.8 V, T = 25 °C unless otherwise noted.

Table 3. Mechanical characteristics

Symbol	Parameter	Test conditions	Min.(1)	Typ.(2)	Max.(1)	Unit
LA_FS	Linear acceleration measurement range			±2		*g*
				±4		
				±8		
				±16		
G_FS	Angular rate measurement range			±125		dps
				±250		
				±500		
				±1000		
				±2000		
LA_So	Linear acceleration sensitivity(3)	FS = ±2	-3%	0.061	+3%	m*g*/LSB
		FS = ±4		0.122		
		FS = ±8		0.244		
		FS = ±16		0.488		
G_So	Angular rate sensitivity(3)	FS = ±125	-3%	4.375	+3%	mdps/LSB
		FS = ±250		8.75		
		FS = ±500		17.50		
		FS = ±1000		35		
		FS = ±2000		70		
LA_SoDr	Linear acceleration sensitivity change vs. temperature(4)	from -40° to +85° delta from T= +25°	-0.024	±0.01	+0.024	%/°C
G_SoDr	Angular rate sensitivity change vs. temperature(4)	from -40° to +85° delta from T= +25°	-0.048	±0.007	+0.048	%/°C
LA_TyOff	Linear acceleration zero-*g* level offset accuracy(5)		-85	±40	+85	m*g*
G_TyOff	Angular rate zero-rate level(5)			±2		dps
LA_OffDr	Linear acceleration zero-*g* level change vs. temperature(4)			±0.1		m*g*/ °C
G_OffDr	Angular rate typical zero-rate level change vs. temperature(4)			±0.015		dps/°C
LA_NL	Linear acceleration nonlinearity(4)	@FS = ±8 *g* Best-fit straight line		±2		%FS
G_NL	Angular rate nonlinearity(4)	@FS =±2000 dps Best-fit straight line		±0.07		%FS

Table 3. Mechanical characteristics (continued)

Symbol	Parameter	Test conditions	Min.(1)	Typ.(2)	Max.(1)	Unit
Rn	Rate noise density in high-performance mode(6)			3.8	11	mdps/√Hz
RnRMS	Gyroscope RMS noise in normal/low-power mode(7)			75		mdps
An	Acceleration noise density in high-performance mode(8)	FS = ±2 *g*		75	170	µ*g*/√Hz
		FS = ±4 *g*		80	170	
		FS = ±8 *g*		90	180	
		FS = ±16 *g*		130	230	
RMS	Acceleration RMS noise in normal/low-power mode(9)(10)	FS = ±2 *g*		1.8		m*g*(RMS)
		FS = ±4 *g*		2.0		
		FS = ±8 *g*		2.4		
		FS = ±16 *g*		3.0		
LA_ODR	Linear acceleration output data rate			1.6(11) 12.5 26 52 104 208 416 833 1666 3332 6664		Hz
G_ODR	Angular rate output data rate			12.5 26 52 104 208 416 833 1666 3332 6664		Hz
Vst	Linear acceleration self-test output change(12)(13)(14)		90		1700	m*g*
	Angular rate self-test output change(15)(16)	FS = ±250 dps	20		80	dps
		FS = ±2000 dps	150		700	dps
Top	Operating temperature range		-40		+85	°C

1. Min/Max values are based on characterization results, not tested in production and not guaranteed
2. Typical specifications are not guaranteed.
3. Sensitivity values after factory calibration test and trimming.

4. Measurements are performed in a uniform temperature setup and they are based on characterization data in a limited number of samples. Not measured during final test for production.
5. Values after factory calibration test and trimming.
6. Gyroscope rate noise density in high-performance mode is independent of the ODR and FS setting.
7. Gyroscope RMS noise in normal/low-power mode is independent of the ODR and FS setting.
8. Accelerometer noise density in high-performance mode is independent of the ODR.
9. Accelerometer RMS noise in normal/low-power mode is independent of the ODR.
10. Noise RMS related to BW = ODR /2 (for ODR /9, typ value can be calculated by Typ *0.6).
11. This ODR is available when accelerometer is in low-power mode.
12. The sign of the linear acceleration self-test output change is defined by the STx_XL bits in *CTRL5_C (14h)*, *Table 64* for all axes.
13. The linear acceleration self-test output change is defined with the device in stationary condition as the absolute value of: OUTPUT[LSb] (self-test enabled) - OUTPUT[LSb] (self-test disabled). 1LSb = 0.061 m*g* at ±2 *g* full scale.
14. Accelerometer self-test limits are full-scale independent.
15. The sign of the angular rate self-test output change is defined by the STx_G bits in *CTRL5_C (14h)*, *Table 63* for all axes.
16. The angular rate self-test output change is defined with the device in stationary condition as the absolute value of: OUTPUT[LSb] (self-test enabled) - OUTPUT[LSb] (self-test disabled). 1LSb = 70 mdps at ±2000 dps full scale.

4.2 Electrical characteristics

@ Vdd = 1.8 V, T = 25 °C unless otherwise noted.

Table 4. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.[1]	Max.	Unit
Vdd	Supply voltage		1.71	1.8	3.6	V
Vdd_IO	Power supply for I/O		1.62		3.6	V
IddHP	Gyroscope and accelerometer current consumption in high-performance mode	ODR = 1.6 kHz		0.75		mA
IddNM	Gyroscope and accelerometer current consumption in normal mode	ODR = 208 Hz		0.5		mA
IddLP	Gyroscope and accelerometer current consumption in low-power mode	ODR = 52 Hz		0.35		mA
LA_IddHP	Accelerometer current consumption in high-performance mode	ODR < 1.6 kHz ODR ≥ 1.6 kHz		180 190		µA
LA_IddNM	Accelerometer current consumption in normal mode	ODR = 208 Hz		85		µA
LA_IddLM	Accelerometer current consumption in low-power mode	ODR = 52 Hz ODR = 12.5 Hz ODR = 1.6 Hz		25 9 4.5		µA
IddPD	Gyroscope and accelerometer current consumption during power-down			10		µA
Ton	Turn-on time			35		ms
V_{IH}	Digital high-level input voltage		0.7 *VDD_IO			V
V_{IL}	Digital low-level input voltage				0.3 *VDD_IO	V
V_{OH}	High-level output voltage	I_{OH} = 4 mA [2]	VDD_IO - 0.2			V
V_{OL}	Low-level output voltage	I_{OL} = 4 mA [2]			0.2	V
Top	Operating temperature range		-40		+85	°C

1. Typical specifications are not guaranteed.
2. 4 mA is the maximum driving capability, i.e. the maximum DC current that can be sourced/sunk by the digital pad in order to guarantee the correct digital output voltage levels V_{OH} and V_{OL}.

4.3 Temperature sensor characteristics

@ Vdd = 1.8 V, T = 25 °C unless otherwise noted.

Table 5. Temperature sensor characteristics

Symbol	Parameter	Test condition	Min.	Typ.(1)	Max.	Unit
TODR(2)	Temperature refresh rate			52		Hz
Toff	Temperature offset(3)		-15		+15	°C
TSen	Temperature sensitivity			256		LSB/°C
TST	Temperature stabilization time(4)				500	µs
T_ADC_res	Temperature ADC resolution			16		bit
Top	Operating temperature range		-40		+85	°C

1. Typical specifications are not guaranteed.
2. When the accelerometer is in Low-Power mode and the gyroscope part is turned off, the TODR value is equal to the accelerometer ODR.
3. The output of the temperature sensor is 0 LSB (typ.) at 25 °C.
4. Time from power ON bit to valid data based on characterization data.

4.4 Communication interface characteristics

4.4.1 SPI - serial peripheral interface

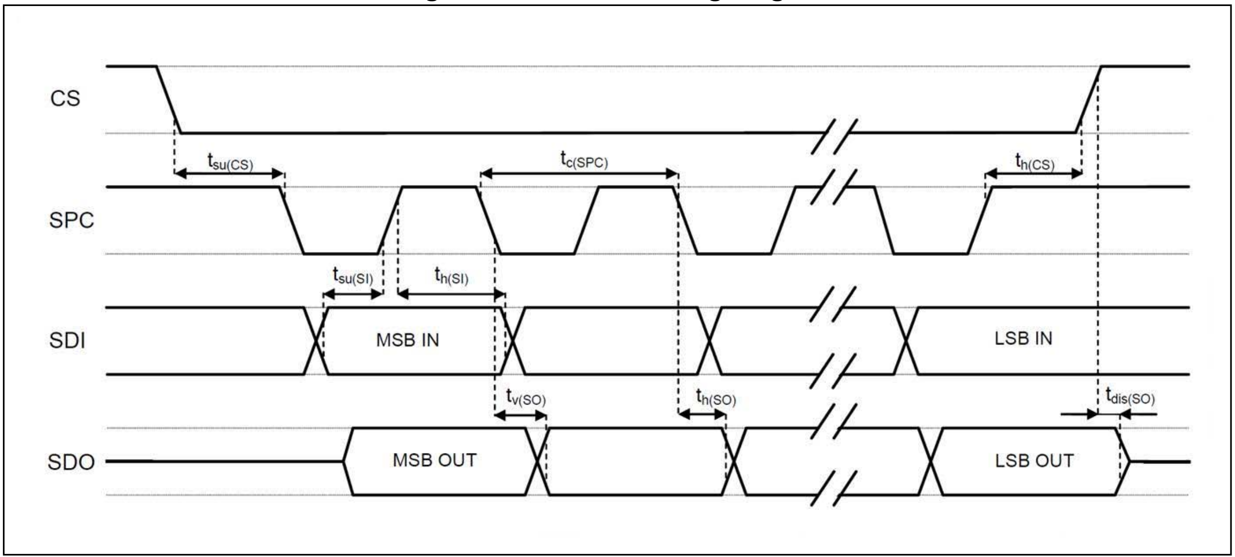
Subject to general operating conditions for Vdd and Top.

Table 6. SPI slave timing values

Symbol	Parameter	Value(1)		Unit
		Min	Max	
$t_{c(SPC)}$	SPI clock cycle	100		ns
$f_{c(SPC)}$	SPI clock frequency		10	MHz
$t_{su(CS)}$	CS setup time	5		ns
$t_{h(CS)}$	CS hold time	20		
$t_{su(SI)}$	SDI input setup time	5		
$t_{h(SI)}$	SDI input hold time	15		
$t_{v(SO)}$	SDO valid output time		50	
$t_{h(SO)}$	SDO output hold time	5		
$t_{dis(SO)}$	SDO output disable time		50	

1. Values are guaranteed at 10 MHz clock frequency for SPI with both 4 and 3 wires, based on characterization results, not tested in production

Figure 3. SPI slave timing diagram



Note: Measurement points are done at 0.2·Vdd_IO and 0.8·Vdd_IO for both input and output ports.